Plastic Packages for Integrated Circuits

Package Outline Drawing
L10.3x3C
10 LEAD DUAL FLAT PACKAGE (DFN)
Rev 4, 3/15

NOTES:
1. Dimensions are in millimeters. Dimensions in ( ) for Reference Only.

2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.

3. Unless otherwise specified, tolerance: Decimal ± 0.05

4. Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).

5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

6. Compliant to JEDEC MO-229-WEED-3 except for E-PAD dimensions.